

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
16 December 2004 (16.12.2004)

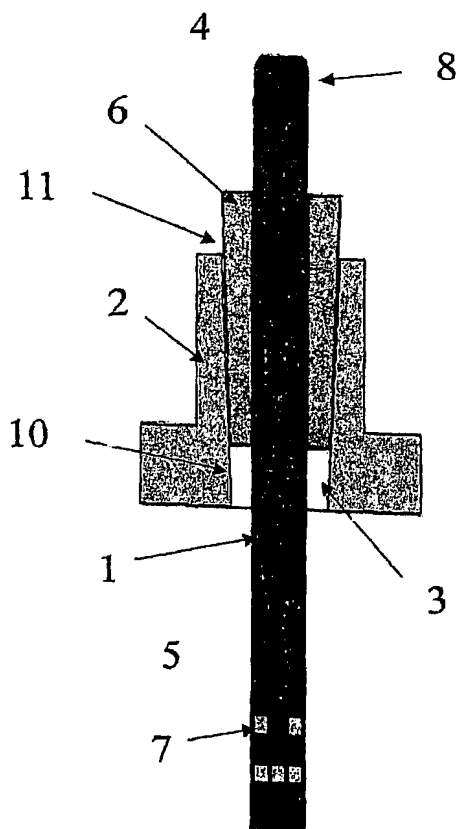
PCT

(10) International Publication Number
WO 2004/109248 A1

- (51) International Patent Classification⁷: **G01L 9/00**
- (21) International Application Number: **PCT/DK2004/000390**
- (22) International Filing Date: **8 June 2004 (08.06.2004)**
- (25) Filing Language: **English**
- (26) Publication Language: **English**
- (30) Priority Data:
PA 2003 00859 10 June 2003 (10.06.2003) DK
- (71) Applicant (for all designated States except US): **DANFOSS A/S [DK/DK]; DK-6430 Nordborg (DK).**
- (72) Inventor; and
- (75) Inventor/Applicant (for US only): **RASMUSSEN, Per, Brandt [DK/DK]; Padholm 6, DK-6440 Augustenborg (DK).**
- (74) Common Representative: **DANFOSS A/S; Patent Department, DK-6430 Nordborg (DK).**
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): **AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.**
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): **ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI,**

[Continued on next page]

(54) Title: **A METHOD FOR FORMING A PRESSURE PROOF ASSEMBLY BETWEEN A COMPONENT AND HOUSE AND SUCH AN ASSEMBLY**



(57) Abstract: The present invention relates to a method for pressure proof and tight assembling of a component to a wall of a house. The method is applicable for assembling components which are sensitive to high temperatures, e.g. for assembling an electronic pressure sensor in a house. According to the invention is component and the house is assembled via a sealing member, e.g. a sleeve, which is pressed into an opening between the component and the house until the yield point is exceeded for at least one of the component, the house and the sealing member.

WO 2004/109248 A1



SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, — with amended claims
GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.